

Z-PACK | Z-PACK Future Bus+

TE Internal #: 5223524-1

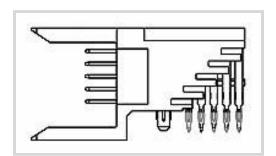
Board-to-Board, 30 Position, 5 Row, 6 Column, Housing for Male Terminals, Sealable, Z-PACK Future Bus+, Backplane Connector

Housings

View on TE.com >



Connectors > PCB Connectors > Backplane Connectors > Backplane Connector Housings



Connector System: Board-to-Board

Number of Positions: **30**Row-to-Row Spacing: **2 mm**

Number of Rows: 5

Number of Columns: 6

Features

Product Type Features

Product Type Features	
Connector System	Board-to-Board
Connector & Housing Type	Housing for Male Terminals
Sealable	Yes
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Positions	30
Number of Rows	5
Number of Columns	6
Contact Features	
Contact Current Rating (Max)	1 A
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2 mm
Dimensions	

2 mm

Row-to-Row Spacing

Usage Conditions



Operating Temperature Range	-55 – 125 °C
Operation/Application	
Circuit Application	Signal

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources.
Solder Process Capability	Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



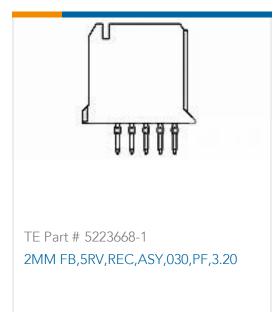












Also in the Series | Z-PACK Future Bus+



Backplane Connector Housings(19)



Hard Metric Backplane Connectors(1)



PCB Headers & Receptacles(35)

Customers Also Bought



TE Part #1367073-1 20 POS SMT CONN, SFP, 15AU



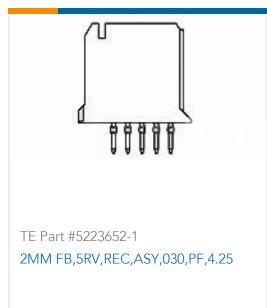
TE Part #2199230-4 M.2 0.5PITCH 4.2H KEY E 15U'' AU



SOLDER WIRE







Documents

CAD Files

3D PDF

3D

Customer View Model ENG_CVM_CVM_5223524-1_O.2d_dxf.zip

English

Board-to-Board, 30 Position, 5 Row, 6 Column, Housing for Male Terminals, Sealable, Z-PACK Future Bus+, Backplane Connector Housings



Customer View Model

ENG_CVM_CVM_5223524-1_O.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5223524-1_O.3d_stp.zip

English

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Product Specifications

Application Specification

English

Agency Approvals

UL Report

English